

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Semiconductor devices – Mechanical and climatic test methods –
Part 30: Preconditioning of non-hermetic surface mount devices prior to
reliability testing**

**Dispositifs à semiconducteurs – Méthodes d’essais mécaniques et climatiques –
Partie 30: Préconditionnement des composants pour montage en surface non
hermétiques avant les essais de fiabilité**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 30: Preconditioning of non-hermetic surface
mount devices prior to reliability testing**

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International Standard IEC 60749-30 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2005 and Amendment 1:2011. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) inclusion of new Clause 3;
- b) expansion of 6.7 on solder reflow;
- c) inclusion of explanatory notes and clarifications.

The text of this International Standard is based on the following documents:

| FDIS | Report on voting |
|--------------|------------------|
| 47/2633/FDIS | 47/2644/RVD |

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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